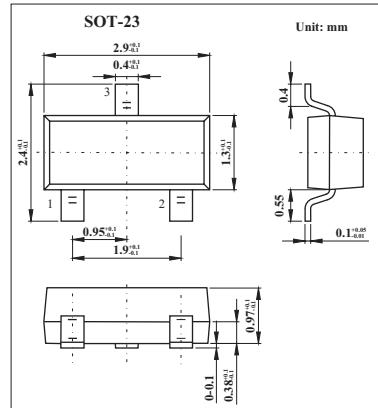


## HSM88AS

### ■ Features

- Proof against high voltage.
- MPAK package is suitable for high density surface mounting and high speed assembly.



### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Value	Unit
Reverse voltage	$V_R$	10	V
Average rectified current	$I_o$	15	mA
Junction temperature	$T_j$	125	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-55 to +125	$^\circ\text{C}$

### ■ Electrical Characteristics $T_a = 25^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	$V_F$	$I_F = 1 \text{ mA}$	350		420	mV
		$I_F = 10 \text{ mA}$	500		580	
Reverse current	$I_R$	$V_R = 2 \text{ V}$			0.2	$\mu\text{A}$
		$V_R = 10 \text{ V}$			10	
Capacitance	C	$V_R = 0 \text{ V}, f = 1 \text{ MHz}$			0.85	pF
Capacitance deviation	$\Delta C$	$V_R = 0 \text{ V}, f = 1 \text{ MHz}$			0.10	pF
Forward voltage deviation	$\Delta V_F$	$I_F = 10 \text{ mA}$			10	mV
ESD-Capability (Note 1)		$C=200\text{pF}$ , Both forward and reverse direction 1 pulse.	30			V

Note

1. Failure criterion ;  $I_R \geq 400\text{nA}$  at  $V_R = 2 \text{ V}$

### ■ Marking

Marking	C1
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